

## PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT7335649

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MS. KRISTI LIN	05/16/2022
MR. ALEXANDER KON-I HO	05/10/2022
MR. PAUL FEUERSTEIN	05/11/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SRAM, LLC
<b>Street Address:</b>	1000 W FULTON MARKET, 4TH FLOOR
<b>City:</b>	CHICAGO
<b>State/Country:</b>	ILLINOIS
<b>Postal Code:</b>	60607
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17746881
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	3126643652
<b>Email:</b>	lserdynski@sram.com
<b>Correspondent Name:</b>	LISA SERDYNSKI
<b>Address Line 1:</b>	1000 W FULTON MARKET, 4TH FLOOR
<b>Address Line 2:</b>	SRAM, LLC
<b>Address Line 4:</b>	CHICAGO, ILLINOIS 60607
<b>ATTORNEY DOCKET NUMBER:</b>	0327UA-US03
<b>NAME OF SUBMITTER:</b>	LISA SERDYNSKI
<b>SIGNATURE:</b>	/Lisa Serdynski/
<b>DATE SIGNED:</b>	05/17/2022
<b>Total Attachments: 5</b>	
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## ASSIGNMENT

WHEREAS, we, the undersigned joint inventors, of residences as listed, are the inventors of certain new and useful subject matter as below entitled, for which application for United States Letters Patent is made, said application having been executed on the date set forth below; and

WHEREAS, SRAM, LLC (hereinafter referred to as "Assignee"), a limited liability company of the State of Delaware, with an address of 1000 West Fulton Market, 4<sup>th</sup> Floor, Chicago, Illinois 60607, desires to acquire the entire right, title and interest in and to the invention, and in and to said application and any Letters Patent that may issue thereon.

NOW, THEREFORE, for and in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we assign to Assignee all right, title and interest in and to: (a) said invention, said application, and all patents which may be granted therefor in the United States and all foreign countries, and all divisions, reissues, reexaminations, continuations, continuations-in-part, and/or extensions thereof; (b) any and all royalties, fees, income, payments, and other proceeds now or hereafter due or payable with respect to any and all of the foregoing; and (c) any and all claims and causes of action with respect to any of the foregoing, whether accruing before, on, or after the date hereof, including all rights to and claims for damages, restitution, and injunctive and other legal and equitable relief for past, present, and future infringement, misappropriation, violation, misuse, breach, or default, with the right but no obligation to sue for such legal and equitable relief and to collect, or otherwise recover, any such damages; the foregoing be held and enjoyed by said Assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this Assignment and sale had not been made.

AND WE DO HEREBY authorize and request the Commissioner of Patents and Trademarks and corresponding bodies in other jurisdictions to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to Assignee, its successors and/or assigns, as assignees of the entire right, title, and interest in and to the invention, for the sole use and benefit of the Assignee, and for its successors and assigns, to the full ends of the terms for which Letters Patent may be granted.

AND we also assign to Assignee, all right, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in SRAM LLC's own name throughout the world, including all rights to publish cautionary appropriate registries and to claim the full benefit of any international agreement between the United States and any foreign country or countries.

We will communicate to Assignee any facts known to us respecting any improvements; and, at the expense of Assignee, we will testify in any legal proceedings and sign all lawful papers, including all powers of attorney, applications, assignments, declarations,

**ASSIGNMENT OF  
INTELLECTUAL PROPERTY RIGHTS**

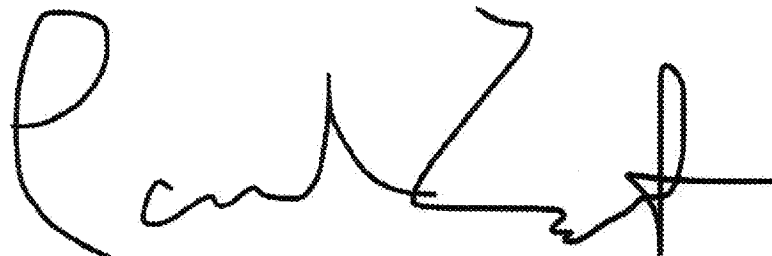
affidavits, exhibits, and any other papers in connection therewith, and otherwise cooperate with Assignee and do everything possible, as requested by Assignee, to perfect and fully vest all right, title, and interest to the foregoing in Assignee in all countries, and to aid Assignee to obtain and enforce proper protection for said invention in all countries.

This assignment shall be binding on the parties' successors, assigns and legal representatives. This assignment may be signed in counterparts, each of which shall be deemed an original and each of which taken together shall constitute one assignment. This assignment may be recorded and/or published. Assignee and/or its designated counsel are hereby requested and authorized to complete the following filing date and application number when known.

Title of Invention:           **CONTROLLER INDICATION**

SRAM No.:                   **0327UA-US03**

United States Serial No.: 17/746,881



Signature of Inventor:

PAUL FEUERSTEIN

Inventor's Name:


BROOKFIELD, USA

Residence (City, Country)

May 11 2022

Date:

Signature of Inventor:



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Inventor's Name:

**KRISTI LIN**

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Residence (City, Country)

**BROOKFIELD, USA**

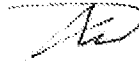
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Date:

**5/16/22**

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Signature of Inventor:



Inventor's Name:

ALEXANDER KON-I HO

Residence (City, Country)

CHICAGO, USA

Date:

May 10 2022